# onsemi

# **MOSFET** - Power, Single N-Channel, SOT-23

# 20 V, 3.2 A

# NTR4501N, NVR4501N

#### Features

- Leading Planar Technology for Low Gate Charge / Fast Switching
- 2.5 V Rated for Low Voltage Gate Drive
- SOT-23 Surface Mount for Small Footprint
- NVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### Applications

- Load/Power Switch for Portables
- Load/Power Switch for Computing
- DC–DC Conversion

#### MAXIMUM RATINGS (T<sub>J</sub>= 25°C unless otherwise stated)

Paramo	Symbol	Value	Unit		
Drain-to-Source Voltage			V <sub>DSS</sub>	20	V
Gate-to-Source Voltage			V <sub>GS</sub>	±12	V
Continuous Drain	,,,		۱ <sub>D</sub>	3.2	А
Current (Note 1)				2.4	А
Steady State Power Dissipation (Note 1)	Stea	dy State	PD	1.25	W
Pulsed Drain Current	t <sub>p</sub> =	= 10 μs	I <sub>DM</sub>	10.0	А
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C
Continuous Source Current (Body Diode)			I <sub>S</sub>	1.6	А
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	100	°C/W
Junction-to-Ambient (Note 2)	$R_{\theta JA}$	300	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

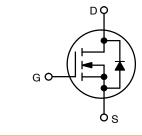
1. Surface-mounted on FR4 board using 1 in sq pad size

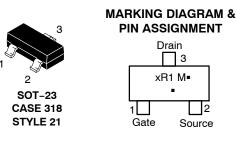
(Cu area = 1.127 in sq [1 oz] including traces).

2. Surface-mounted on FR4 board using the minimum recommended pad size.

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Typ	I <sub>D</sub> Max (Note 1)
20 V	70 mΩ @ 4.5 V	3.6 A
20 V	88 mΩ @ 2.5 V	3.1 A







TR1 = Device Code for NTR4501N

VR1 = Device Code for NVR4501N

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTR4501NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NVR4501NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

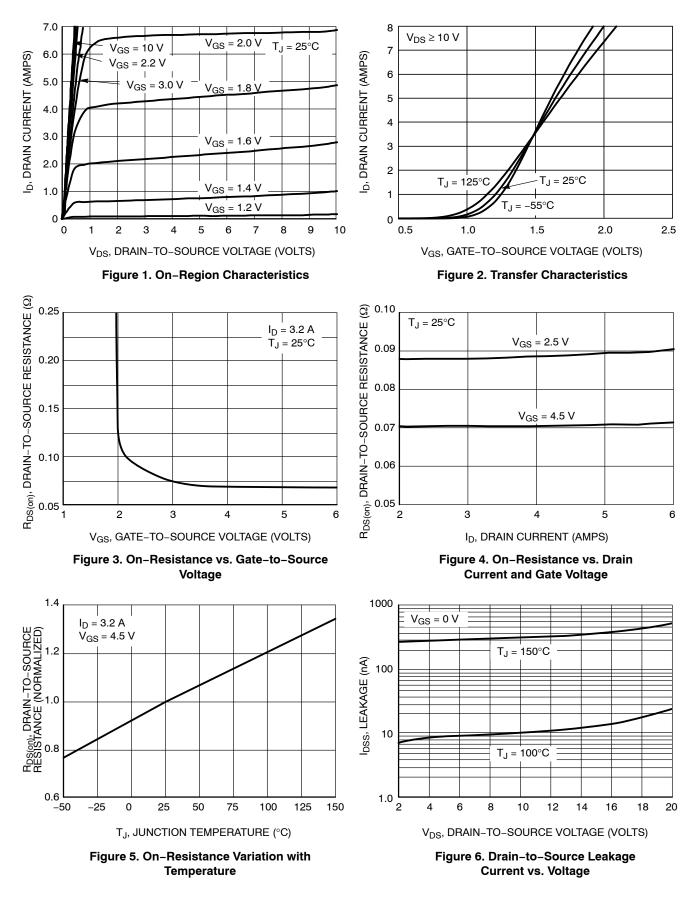
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise specified)

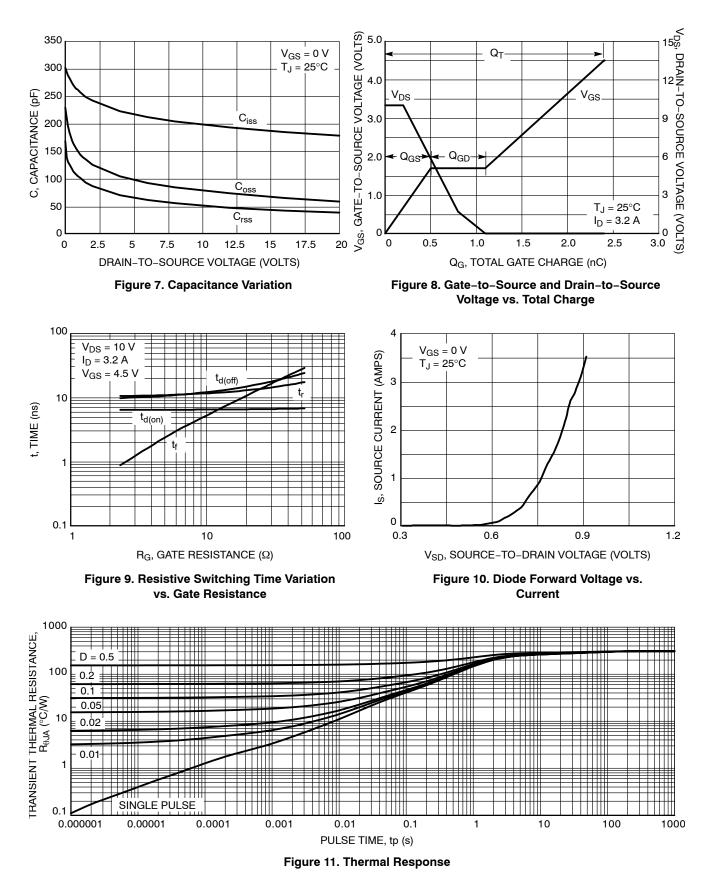
Parameter	Symbol	Test Condition	Min	Тур	Max	Units
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage (Note 3)	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A	20	24.5		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>			22		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS}$ = 0 V, $T_J$ = 25°C			1.5	μΑ
		V <sub>DS</sub> = 16 V, T <sub>J</sub> = 85°C			10	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ±12 V			±100	nA
ON CHARACTERISTICS			-			
Gate Threshold Voltage (Note 3)	V <sub>GS(TH)</sub>	$V_{GS}$ = $V_{DS}$ , $I_D$ = 250 $\mu$ A	0.65		1.2	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>			-2.3		mV/°C
Drain-to-Source On Resistance	_	$V_{GS}$ = 4.5 V, I <sub>D</sub> = 3.6 A		70	80	mΩ
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 3.1 A		88	105	
Forward Transconductance	<b>9</b> FS	$V_{DS} = 5.0 \text{ V}, \text{ I}_{D} = 3.6 \text{ A}$		9		S
CHARGES AND CAPACITANCES				-	-	
Input Capacitance	C <sub>iss</sub>			200		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 10 V		80		
Reverse Transfer Capacitance	C <sub>rss</sub>	VDS - 10 V		50		
Total Gate Charge	Q <sub>G(TOT)</sub>			2.4	6.0	nC
Gate-to-Source Gate Charge	Q <sub>GS</sub>	$V_{GS}$ = 4.5 V, $V_{DS}$ = 10 V, I <sub>D</sub> = 3.6 A		0.5		]
Gate-to-Drain Charge	Q <sub>GD</sub>	1 <u>0</u> – 0.071		0.6		
SWITCHING CHARACTERISTICS (Note 4)				-	-	
Turn-On Delay Time	t <sub>d(on)</sub>			6.5	13	ns
Rise Time	t <sub>r</sub>	Vcs = 4.5 V. Vcs = 10 V.		12	24	
Turn-Off Delay Time	t <sub>d(off)</sub>	$\begin{array}{l} {\sf V}_{GS} = {\rm 4.5~V}, {\sf V}_{DS} = {\rm 10~V}, \\ {\sf I}_{D} = {\rm 3.6~A}, {\sf R}_{G} = {\rm 6.0~\Omega} \end{array}$		12	24	
Fall Time	t <sub>f</sub>			3	6	
SOURCE-DRAIN DIODE CHARACTERISTICS	3		•	•	•	
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS}$ = 0 V, $I_{SD}$ = 1.6 A		0.8	1.2	V
Reverse Recovery Time	t <sub>RR</sub>			7.1		ns
Charge Time	ta	$V_{GS} = 0 V,$		5		
Discharge Time	t <sub>b</sub>	d <sub>IS</sub> /d <sub>t</sub> = 100 A/μs, I <sub>S</sub> = 1.6 A		1.9		
Reverse Recovery Charge	Q <sub>RR</sub>			3.0		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse width  $\leq$  300 µs, duty cycle  $\leq$  2%. 4. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



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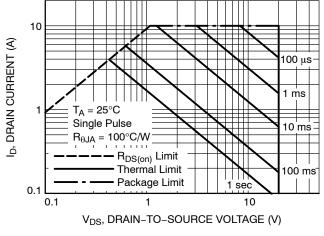


Figure 12. Safe Operating Area (SOA)

# semi



#### SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318**

**ISSUE AU** 

DATE 14 AUG 2024













XXX = Specific Device Code М = Date Code

= Pb-Free Package .

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



MILLIMETERS					
DIM	MIN	NOM	МАХ		
А	0.89	1.00	1.11		
A1	0.01	0.06	0.10		
b	0.37	0.44	0.50		
с	0.08	0.14	0.20		
D	2.80	2.90	3.04		
E	1.20	1.30	1.40		
е	1.78	1.90	2.04		
L	0.30	0.43	0.55		
L1	0.35	0.54	0.69		
Ηe	2.10	2.40	2.64		
Т	0°		10°		

NOTES:

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS: 1.

2. MILLIMETERS.

MILLIME IERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE 3.

BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, 4. PROTRUSIONS, OR GATE BURRS.

#### RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **STYLES ON PAGE 2**

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#### SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CÁSE 318** ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	I	
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE	2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE	3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	I PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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